| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|----------|------|---|---|---------------------|---------|------------------|
| L1 | 91 | substrate and (first adj chip) and (second adj chip) and (package or packaging) and (bump or bumps) and (encapsulat\$4) | USPAT | OR | OFF | 2005/01/04 13:41 |
| L2 | 84 | substrate and (first adj chip) and (second adj chip) and (package or packaging) and (bump or bumps) and (encapsulat\$4) | US-PGPUB; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/01/04 13:41 |